CMKD2836
CMKD2838

**SURFACE MOUNT
DUAL PAIR
HIGH SPEED SILICON
SWITCHING DIODES**

ULTRAmini™

SOT-363 CASE

Central
Semiconductor Corp.

www.centralsemi.com

DESCRIPTION:
The CENTRAL SEMICONDUCTOR CMKD2836 and CMKD2838 types consist of four high speed switching diodes arranged in two electrically isolated configurations (Common Anode and Common Cathode). These devices are manufactured by the epitaxial planar process, in an epoxy molded ULTRAmini™ surface mount package, designed for high speed switching applications.

The following configurations are available:

CMKD2836 DUAL PAIR, COMMON ANODE   **MARKING CODE: K36**
CMKD2838 DUAL PAIR, COMMON CATHODE   **MARKING CODE: K38**

MAXIMUM RATINGS: (T_A=25°C)

	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	75	V
Average Forward Current	I_O	200	mA
Peak Forward Current	I_{FM}	300	mA
Power Dissipation	P_D	350	mW
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	357	°C/W

ELECTRICAL CHARACTERISTICS PER DIODE: (T_A=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_R	V_R=50V			100	nA
BV_R	I_R=100µA	75			V
V_F	I_F=10mA			1.0	V
V_F	I_F=50mA			1.0	V
V_F	I_F=100mA			1.2	V
C_T	V_R=0, f=1.0MHz		1.5	4.0	pF
t_{rr}	I_R=I_F=10mA, R_L=100Ω, Rec. to 1.0mA			4.0	ns

R4 (13-January 2010)

CMKD2836
CMKD2838

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SOT-363 CASE - MECHANICAL OUTLINE
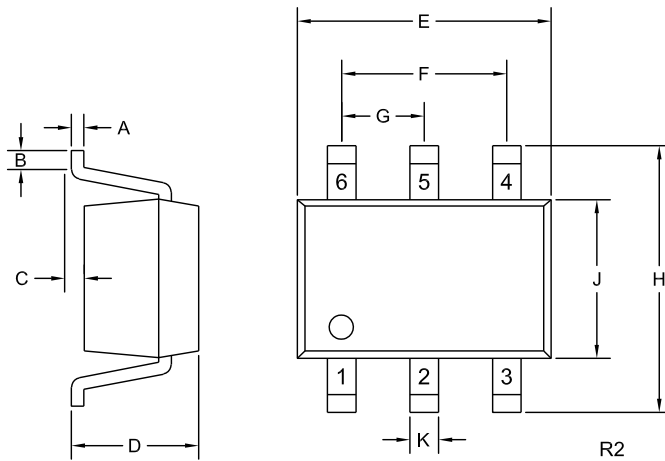
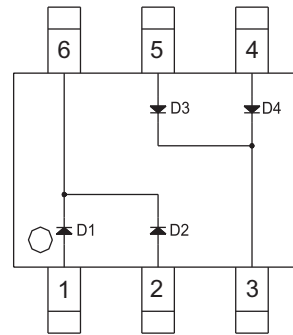| DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.004	0.010	0.10	0.25
B	0.005	-	0.12	-
C	0.000	0.004	0.00	0.10
D	0.031	0.043	0.80	1.10
E	0.071	0.087	1.80	2.20
F	0.051		1.30	
G	0.026		0.65	
H	0.075	0.091	1.90	2.30
J	0.043	0.055	1.10	1.40
K	0.006	0.012	0.15	0.30

SOT-363 (REV: R2)

PIN CONFIGURATIONS
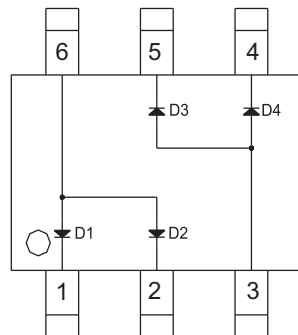
CMKD2836

LEAD CODE:
1) Cathode D1
2) Cathode D2
3) Anode D3, D4
4) Cathode D4
5) Cathode D3
6) Anode D1, D2

MARKING CODE: K36

CMKD2838

LEAD CODE:
1) Anode D1
2) Anode D2
3) Cathode D3, D4
4) Anode D4
5) Anode D3
6) Cathode D1, D2

MARKING CODE: K38

R4 (13-January 2010)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

• Supply management (Customer portals)
• Inventory bonding
• Consolidated shipping options
• Custom bar coding for shipments
• Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

• Free quick ship samples (2nd day air)
• Online technical data and parametric search
• SPICE models
• Custom electrical curves
• Environmental regulation compliance
• Customer specific screening
• Up-screening capabilities
• Special wafer diffusions
• PbSn plating options
• Package details
• Application notes
• Application and design sample kits
• Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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